4-2002
299863 ET U.S. DEPARTMENT OF COMMERCE U.S. Patent And Trademark Office
cord the attached original documents or copy thereof:
2. Name and address of receiving party(ies):
Name: Flextronics Photonics PPT
Internal Address:
Street Address:
City: Hillsboro
State: OR Zip: 97123
Additional name(s) & address(es) attached?
Yes No
$\begin{array}{ c c c c c c c c c c c c c c c c c c c$
attached? Yes No 6. Total number of applications and patents involved: [5]
7. Total fee (37 CFR 3.41): \$200.00
Check Enclosed
Fee Transmittal Enclosed
Charge the indicated fees to the below mentioned deposit account.
8. Deposit Account No.:
SE THIS SPACE
mation is true and correct and any attached copy is a January 14, 2002
January VI, 2002
Signature Date
Signature Date ver sheet, attachments, documents: [4]

PATENT REEL: 012607 FRAME: 0553

PATENT ASSIGNMENT AGREEMENT

This Patent Assignment Agreement (the "Agreement") is entered into by and between Tektronix, inc., an Oregon corporation with offices in Beaverton, Oregon ("Tektronix"), Maxtek Components Corporation, a wholly-owned subsidiary of Tektronix with offices in Beaverton, Oregon ("Maxtek"), and Flextronics Photonics PPT, Inc. with offices in Hillsboro, Oregon ("Assignee").

Α. Tektronix is the owner of the United States and foreign patents listed in the attached Schedule A (the "Assigned Patents").

Assignee is a licensee under the Assigned Patents pursuant to a License Agreement Β. between Photonic Packaging Technologies, Inc. and Tektronix dated July 20, 1990.

Maxtek is a licensee under the Assigned Patents pursuant to Section 2.8 of the "HCO C. Technology Transfer Agreement," dated May 27, 1994 (the "HCO Agreement").

D. Assignee now desires to acquire Tektronix' interest in the Assigned Patents and to restrict Maxtek's rights under the HCO Agreement.

Now, therefore, the parties agree as follows:

For the sum of 1.

to be paid to Tektronix by Assignee within ten (10) business days following the execution of this Agreement, and for other good and valuable consideration, the receipt and adequacy of which is hereby acknowledged, Tektronix hereby sells, assigns, transfers and conveys its entire right, title, and interest in and to the Assigned Patents (including any reissue patents and patent applications) to Assignee, subject to existing licenses to Maxtek and to Innovacomm Technologies, Inc., and together with all claims, demands, or causes of action that Tektronix has or might have by reason of any infringement of said Assigned Patents prior to the effective date of this agreement, including the right to collect damages for such past infringement in the name of Assignee, subject, however, to a reservation by Tektronix of a personal, non-exclusive, royalty-free, world-wide license, without the right to grant sublicenses, to make, have made, use and sell or otherwise dispose of products embodying or made in accordance with the inventions described and claimed in said Assigned Patents.

to be paid to Maxtek by Assignee within ten (10) For the sum of 2. business days following the execution of this Agreement, and for other good and valuable consideration, the receipt and adequacy of which is hereby acknowledged, Maxtek agrees to not assign or sublicense to a third party any of its rights in the Assigned Patents after the effective date of this Agreement without the prior written consent of Assignee.

The parties agree to execute such further documents, agreements, or consents as may be 3. required to effectuate this Agreement.

Each party shall bear its own attorney fees and costs related to this transaction. 4.

This Agreement shall be binding upon and shall inure to the benefit of the parties and their 5. respective successors and assigns.

Page 1 of 3

PATENT REEL: 012607 FRAME: 0554 6. The effective date of this Agreement shall be latter execution date set out below.

TEKTRONIX, INC.

By: James F. Dalton

Its: Vice President & General Counsel Date:

FLEXTRONICS PHOTONICS PPT, INC. By. Randy S. Randa

Its: General Manager

Date: 1/16/02_

MAXTEK COMPONENTS CORPORATION

By: Thomas S. Buzak

Its: President

Date:

Page 2 of 3

PATENT REEL: 012607 FRAME: 0555

SCHEDULE A

Assigned Patents

Country	Patent No.	Expiration Date	<u>Title</u>
United States	4,722,586	4/12/2005	Electro-Optical Transducer Module
Canada	1309484	10/27/2009	Electro-Optical Transducer Module
Japan	1846775	4/11/2006	Electro-Optical Transducer Module
United States	4,702,547	7/28/2006	Method for Attaching an Optical Fiber to a Substrate to Form an Optical Fiber Package
Japan	1860628	7/10/2007	Method for Attaching an Optical Fiber to a Substrate to Form an Optical Fiber Package
United States	4,818,263	6/11/2007	Method and Apparatus for Precisely Positioning Microlenses on Optical Fibers
United States	4,997,253	4/3/2009	Electro-Optical Transducer Module and a Method of Fabricating Such a Module
United States	4,936,646	8/23/2009	Temperature Compliant Tube for Fiber Optic Components

Page 3 of 3

PATENT REEL: 012607 FRAME: 0556

RECORDED: 02/12/2002

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